Panasonic

MOS FET FC4B22180L1

FC4B22180L1

Gate resistor installed Dual N-channel MOS FET

For lithium-ion secondary battery protection circuits

Features

- Low source-source ON resistance:Rss(on) typ. = $10 \text{ m}\Omega(\text{VGS} = 3.8 \text{ V})$
- CSP(Chip Size Package)
- · RoHS compliant (EU RoHS / MSL:Level 1 compliant)
- Marking Symbol: 17

Packaging

Embossed type (Thermo-compression sealing): 1 000 pcs / reel (standard)

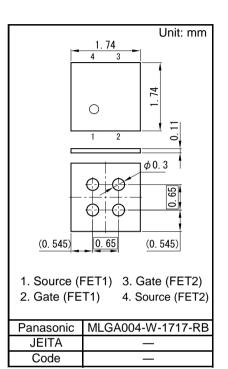
■ Absolute Maximum Ratings Ta = 25 °C									
Parameter		Symbol	Rating	Unit					
Source-source Voltage		VSS	20	V					
Gate-source Voltage		VGS	±8	V					
Source Current	DC ^{*1}	IS1	5	Α					
	DC ^{*2}	IS2	10	А					
	Pulse *3	ISp	50	А					
Total Power Dissipation	DC *1	PD1	0.4	W					
	DC *2	PD2	1.5	W					
Channel Temperature		Tch	150	°C					
Storage Temperature Range		Tstg	-55 to +150	°C					
Thermal Resistance (ch-a)	DC ^{*1}	Rth1	312	°C/W					
	DC ^{*2}	Rth2	83	°C/W					
Note *1 Mounted on FR4 board		-							

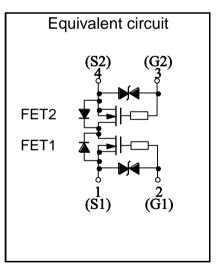
(25.4mm × 25.4mm × t1.0mm, 36μm Copper)

*2 Mounted on Ceramic substrate

(70 mm imes 70 mm imes t1.0 mm).

*3 t = 10 $\mu s,~Duty~Cycle$ \leq 1 %







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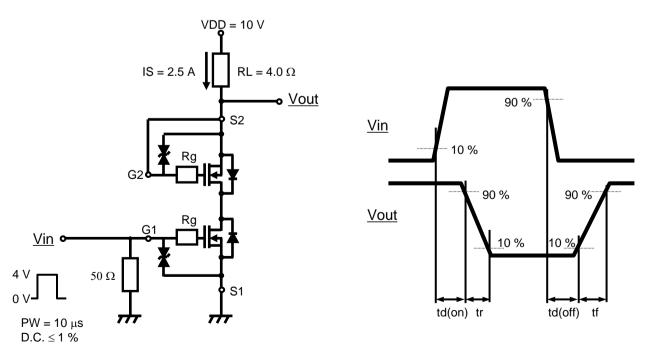
■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Source-source Breakdown Voltage	VSSS	IS = 1 mA, VGS = 0 V	20			V	
Zero Gate Voltage Source Current	ISSS	VSS = 20 V, VGS = 0 V			1.0	μA	
Gate-source Leakage Current	IGSS	$VGS = \pm 8 V, VSS = 0 V$			±10)	
	1885	$VGS = \pm 5 V, VSS = 0 V$			±1.0	μA	
Gate-source Threshold Voltage	Vth	IS = 0.64 mA, VSS = 10 V	0.35	0.90	1.4	V	
Source-source On-state Resistance	RSS(on)1	IS = 2.5 A, VGS = 4.5 V	7	9.4	11.9		
	RSS(on)2	IS = 2.5 A, VGS = 3.8 V	7.3	10	12.9	mΩ	
	RSS(on)3	IS = 2.5 A, VGS = 3.1 V	8.1	11.1	15.8		
	RSS(on)4	IS = 2.5 A, VGS = 2.5 V	8.6	13.4	22.6		
Body Diode Forward Voltage	VF(s-s)	IF = 2.5 A, VGS = 0 V		0.8	1.2	V	
Input Capacitance ^{*1}	Ciss			2440		pF	
Output Capacitance ^{*1}	Coss	VSS = 10 V, VGS = 0 V, f = 1 MHz		200			
Reverse Transfer Capacitance ^{*1}	Crss			160			
Turn-on delay Time *1,*2	td(on)	VDD = 10 V, VGS = 0 to 4.0 V		0.9			
Rise Time ^{*1,*2}	tr	IS = 2.5 A		1.6		μs	
Turn-off delay Time *1,*2	td(off)	VDD = 10 V, VGS = 4.0 to 0 V		5		μS	
Fall Time ^{*1,*2}	tf	IS = 2.5 A		2.4			
Total Gate Charge ^{*1}	Qg	VDD = 10 V		23			
Gate-source Charge ^{*1}	Qgs	VGS = 0 to 4.0 V,		6		nC	
Gate-drain Charge ^{*1}	Qgd	IS = 2.5 A		5			

Note Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

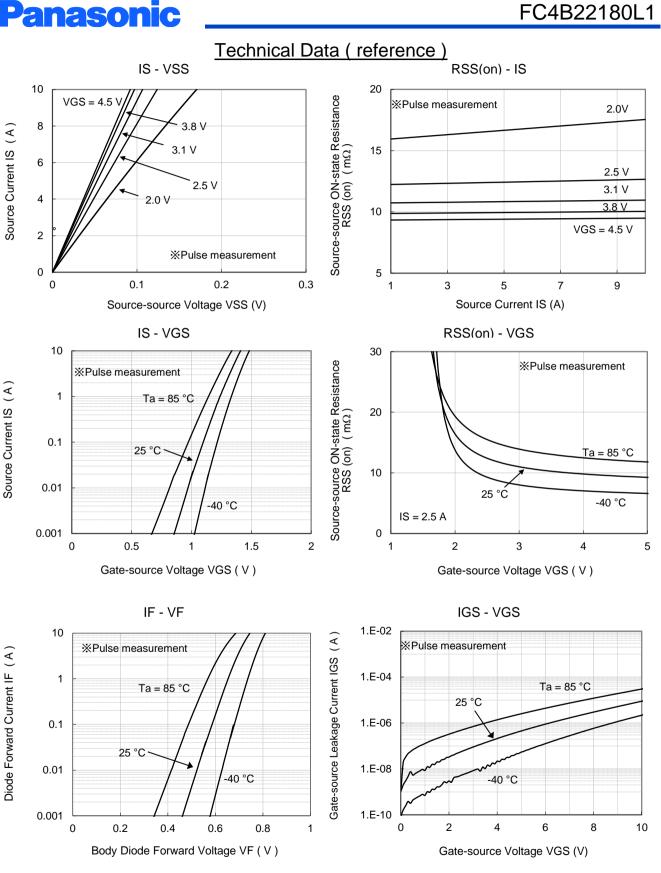
*1 Guaranteed by design, not subject to production testing

*2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time



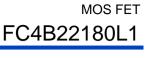
Note2 : Measurement circuit

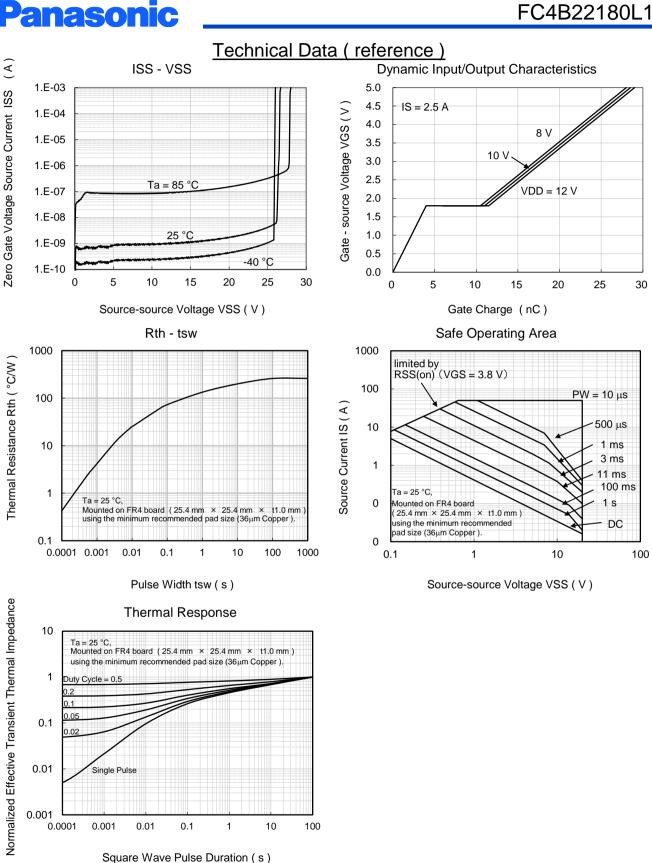
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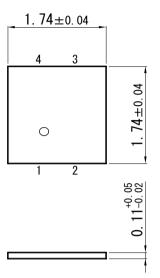
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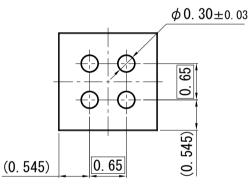


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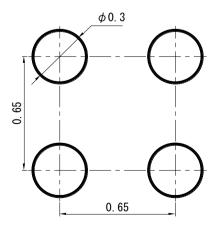
■ Outline (MLGA004-W-1717-RB)

Unit: mm





■ Land Pattern (Reference)



Unit: mm

Established : 2015-10-23 Revised : ###-##-##

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